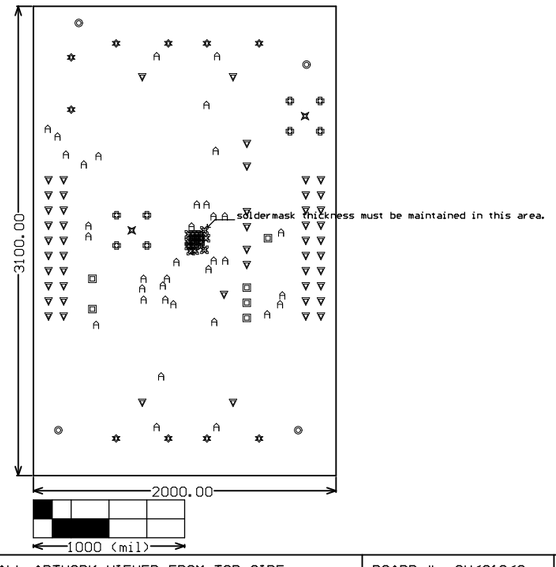
| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|---|---|---|---|---|---|
| 1 | Top Overlay | | | | |
| 2 | Top Solder | Solder Resist | 0.40mil | 3.5 | |
| 3 | Top Layer | Copper | 1.40mil | | |
| 4 | Dielectric1 | FR-4 High TG | 12.60mil | 4.8 | |
| 5 | GND_PLANE | Copper | 1.40mil | | |
| 6 | Dielectric2 | FR-4 High TG | 30.00mil | 4.8 | |
| 7 | POWER_PLANE | Copper | 1.40mil | | |
| 8 | Dielectric3 | FR-4 High TG | 12.60mil | 4.8 | |
| 9 | Bottom Layer | Copper | 1.40mil | | |
| 10 | Bottom Solder | Solder Resist | 0.40mil | 3.5 | |
| 11 | Bottom Overlay | | | | |

| Symbol | Hit Count | Finished Hole Size | Plated | Hole Type |
|---|---|---|---|---|
| ✖ | 2 | 62.00mil (1.575mm) | PTH | Round |
| ◎ | 4 | 63.00mil (1.600mm) | PTH | Round |
| ▣ | 6 | 35.00mil (0.889mm) | PTH | Round |
| ✿ | 8 | 67.00mil (1.702mm) | PTH | Round |
| ✱ | 10 | 18.00mil (0.457mm) | PTH | Round |
| ✖ | 19 | 6.00mil (0.152mm) | PTH | Round |
| A | 36 | 10.00mil (0.254mm) | PTH | Round |
| ▽ | 51 | 40.00mil (1.016mm) | PTH | Round |
| | 136 Total | | | |




DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3100MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 12 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[ ] GREEN [ ] BLUE [X] OTHER RED
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [X] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [ ] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: TDC7201-ZAX-EVM
DESIGNED FOR: Public Release
FILE NAME: SV601269A.PcbDoc

| | | | |
|---|---|---|---|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: SV601269 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = [illegible]ions | | | |
| PLOT NAME = Fabrication Drawing | GENERATED : 3/31/2016 4:26:30 PM | TEXAS INSTRUMENTS | |

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| ENGINEER: | LAYOUT BY: |
|---|---|
| Vishy Viswanathan | Krypton Solutions |
| SCALE: 1.00 | ALTIUM DESIGNER VERSION: 16.0.1.132 |